

# **REGULATORY COMPLIANCE**











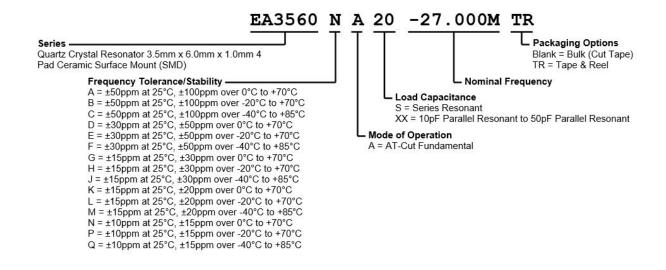
### **ITEM DESCRIPTION**

Quartz Crystal Resonator 3.5mm x 6.0mm x 1.0mm 4 Pad Ceramic Surface Mount (SMD)

ELECTRICAL SPECIFICAT	TIONS
Nominal Frequency	10MHz to 48MHz
Frequency Tolerance/Stability	±50ppm at 25°C, ±100ppm over 0°C to +70°C  ±50ppm at 25°C, ±100ppm over -20°C to +70°C  ±50ppm at 25°C, ±100ppm over -40°C to +85°C  ±30ppm at 25°C, ±50ppm over -20°C to +70°C  ±30ppm at 25°C, ±50ppm over -20°C to +70°C  ±30ppm at 25°C, ±50ppm over -40°C to +85°C  ±15ppm at 25°C, ±50ppm over -40°C to +70°C  ±15ppm at 25°C, ±30ppm over -20°C to +70°C  ±15ppm at 25°C, ±30ppm over -20°C to +70°C  ±15ppm at 25°C, ±20ppm over -40°C to +85°C  ±15ppm at 25°C, ±20ppm over -20°C to +70°C  ±15ppm at 25°C, ±20ppm over -20°C to +70°C  ±15ppm at 25°C, ±20ppm over -20°C to +70°C  ±10ppm at 25°C, ±15ppm over -20°C to +70°C  ±10ppm at 25°C, ±15ppm over -20°C to +70°C  ±10ppm at 25°C, ±15ppm over -40°C to +85°C
Aging at 25°C	±3ppm/year Maximum
Load Capacitance	Series Resonant, 10pF Parallel Resonant to 50pF Parallel Resonant
Shunt Capacitance	5pF Maximum
Equivalent Series Resistance	60 Ohms Maximum over Nominal Frequency of 10MHz to 19.999999MHz 50 Ohms Maximum over Nominal Frequency of 20MHz to 34.999999MHz 40 Ohms Maximum over Nominal Frequency of 35MHz to 48MHz
Mode of Operation	AT-Cut Fundamental
Drive Level	100μWatts Maximum
Spurious Response	Measured from Fo to Fo +5000ppm -3dB Minimum
Storage Temperature Range	-40°C to +85°C
Insulation Resistance	Measured at 100Vdc 500 Megaohms Minimum

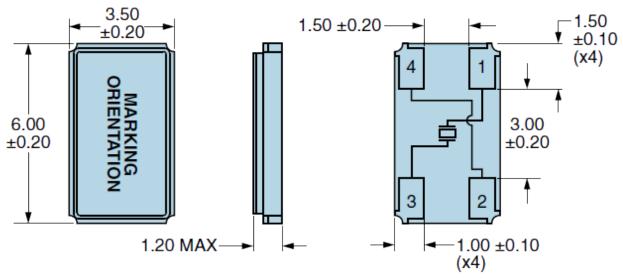


#### **PART NUMBERING GUIDE**





#### **MECHANICAL DIMENSIONS**

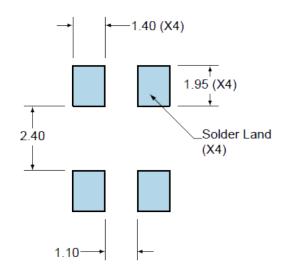


Note: Chamfer not shown.

#### Seam Sealed

Terminal Plating Thickness: Gold (0.3 to 1.0μm) over Nickel (1.27 to 8.89μm).

### SUGGESTED SOLDER PAD LAYOUT



PIN	CONNECTION
1	Crystal
2	Case/Ground
3	Crystal
4	Case/Ground

All Tolerances are ±0.1

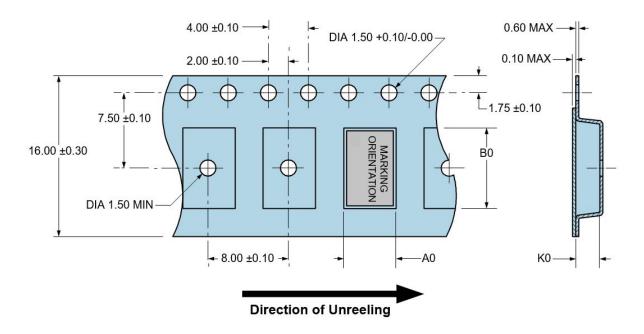
### **All Dimensions in Millimeters**

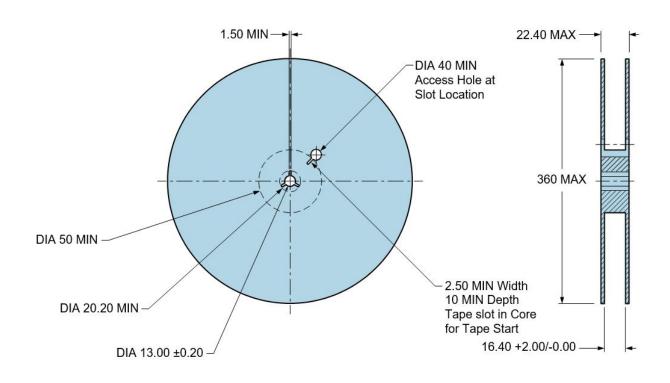


### **TAPE & REEL DIMENSIONS**

Quantity per Reel: 1,000 Units

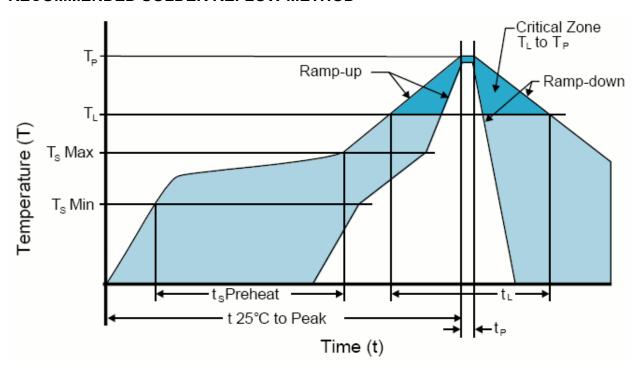
All Dimensions in Millimeters
Compliant to EIA-481







# **RECOMMENDED SOLDER REFLOW METHOD**



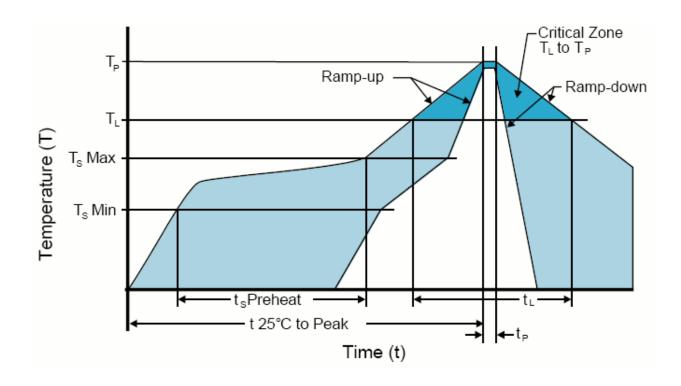
HIGH TEMPERATURE INFRARED/CONVECTION		
T <sub>s</sub> MAX to T <sub>L</sub> (Ramp-up Rate)	3°C/Second Maximum	
Preheat		
- Temperature Minimum (T <sub>s</sub> MIN)	150°C	
- Temperature Typical (T <sub>s</sub> TYP)	175°C	
- Temperature Maximum(T <sub>s</sub> MAX)	200°C	
- Time (t <sub>s</sub> MIN)	60 - 180 Seconds	
Ramp-up Rate (T <sub>L</sub> to T <sub>P</sub> )	3°C/Second Maximum	
Time Maintained Above:		
- Temperature (T <sub>L</sub> )	217°C	
- Time (t <sub>L</sub> )	60 - 150 Seconds	
Peak Temperature (T <sub>P</sub> )	260°C Maximum for 10 Seconds Maximum	
Target Peak Temperature(T <sub>P</sub> Target)	250°C +0/-5°C	
Time within 5°C of actual peak (t <sub>p</sub> )	20 - 40 Seconds	
Ramp-down Rate	6°C/Second Maximum	
Time 25°C to Peak Temperature (t)	8 Minutes Maximum	
Moisture Sensitivity Level	Level 1	
Additional Notes	Temperatures shown are applied to body of device.	

### **High Temperature Manual Soldering**

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)



# **RECOMMENDED SOLDER REFLOW METHOD**



LOW TEMPERATURE INFRARED/CONVECTION		
T <sub>s</sub> MAX to T <sub>L</sub> (Ramp-up Rate)	5°C/Second Maximum	
Preheat		
- Temperature Minimum (T <sub>S</sub> MIN)	N/A	
- Temperature Typical (T <sub>s</sub> TYP)	150°C	
- Temperature Maximum(T <sub>s</sub> MAX)	N/A	
- Time (t <sub>s</sub> MIN)	30 - 60 Seconds	
Ramp-up Rate (T <sub>L</sub> to T <sub>P</sub> )	5°C/Second Maximum	
Time Maintained Above:		
- Temperature (T <sub>L</sub> )	150°C	
- Time (t <sub>L</sub> )	200 Seconds Maximum	
Peak Temperature (T <sub>P</sub> )	245°C Maximum	
Target Peak Temperature(T <sub>P</sub> Target)	245°C Maximum 2 Times/230°C Maximum 1Time	
Time within 5°C of actual peak (t <sub>P</sub> )	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time	
Ramp-down Rate	5°C/Second Maximum	
Time 25°C to Peak Temperature (t)	N/A	
Moisture Sensitivity Level	Level 1	
Additional Notes	Temperatures shown are applied to body of device.	

#### **Low Temperature Manual Soldering**

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)